Hong Kong Exchanges and Clearing Limited and The Stock Exchange of Hong Kong Limited take no responsibility for the contents of this announcement, make no representation as to its accuracy or completeness and expressly disclaim any liability whatsoever for any loss howsoever arising from or in reliance upon the whole or any part of the contents of this announcement.

NEXCHIP SEMICONDUCTOR CORPORATION
合肥晶合集成電路股份有限公司
(A joint stock company incorporated in the People's Republic of China with limited liability)
(Stock Code: 2249)

ANNOUNCEMENT ON THE PROGRESS OF DISCLOSEABLE AND CONNECTED TRANSACTION ENTERING INTO THE CAPITAL INCREASE AGREEMENT

Reference is made to the announcement of Nexchip Semiconductor Corporation (合肥晶合集成電路股份有限公司) (the "**Company**") dated November 5, 2026 (the "**Announcement**") in relation to the Company's proposed entering into the Capital Increase Agreement with the Target Company, Hefei Construction Investment and Hefei Qinhe, pursuant to which, the Company, Hefei Construction Investment and Hefei Qinhe will subscribe for the increased registered capital of the Target Company by contributing an aggregate amount of RMB9,100 million in cash (the "**Capital Increase**"). Unless the context otherwise requires, capitalized terms used herein shall have the same meanings as those defined in the Announcement.

The Board announces that on November 19, 2026, the Company, the Target Company, Hefei Construction Investment and Hefei Qinhe have entered into the Capital Increase Agreement. Please refer to the Announcement for the principal terms of the Capital Increase Agreement and details of the Capital Increase.

As agreed under the Capital Increase Agreement, the Capital Increase Agreement shall be established upon the signature or sealing by the legal representatives or authorized representatives of each party and the affixing of their respective company chops, and shall become effective upon the consideration and approval of the Capital Increase by the general meeting of the Company. Therefore, the Capital Increase Agreement and the Capital Increase contemplated thereunder remain subject to approval by the Independent Shareholders at the EGM to be convened by the Company.

As disclosed in the Announcement, a circular containing, among others, further details regarding the Capital Increase Agreement and the Capital Increase contemplated thereunder, a letter from the Independent Board Committee, a letter of advice from the Independent Financial Adviser and the notice of the EGM, is expected to be published and dispatched to the Shareholders on or before December 31, 2026. The Company will make further announcement(s) on the subsequent progress of the Capital Increase as appropriate in accordance with the applicable provisions of the Listing Rules.

By order of the Board
Nexchip Semiconductor Corporation
合肥晶合集成電路股份有限公司
Mr. Tsai Kuo-Chih
Executive Director and Chairperson of the Board

Hong Kong, November 19, 2026

As at the date of this announcement, the Board comprises: (i) Mr. Tsai Kuo-Chih and Mr. Zhu Caiwei as executive Directors; (ii) Mr. Lu Qinhang, Mr. Qiu Wensheng, Mr. Guo Zhaozhi and Ms. Yang Guoqing as non-executive Directors; and (iii) Prof. Sheng Mingquan, Prof. Lin Zhiting and Mr. Chen Ting as independent non-executive Directors.